



Statement of Materials, Construction

LEAD-FREE -- 16L-QFN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Ag Plated Cu	0.01787	Cu	7440-50-8	0.01737	40.85	97.23
				Fe	7439-89-6	0.00042	0.98	2.34
				Zn	7440-66-6	0.00002	0.05	0.12
				P	7723-14-0	0.00001	0.01	0.03
				Silver (plating)	7440-22-4	0.00005	0.12	0.28
2	Die	Silicon Chip	0.00102	Si	7440-21-3	0.00101	2.38	99.5
3	Die Attach Material	Conductive Epoxy	0.00013	Silver	7440-22-4	0.0001	0.22	75
				Epoxy Resin	Proprietary	0.0000	0.04	15
				Amine	Proprietary	0.0000	0.01	3.3
				Gamma Butyrolactone	96480	0.0000	0.01	3.3
				Metal Oxide	Proprietary	0.0000	0.01	3.3
4	Wire	Gold	0.00007	Au	7440-57-5	0.0001	0.16	99.99
5	Lead Finish	Tin	0.00058	Sn	7440-31-5	0.0006	1.37	100
6	Encapsulation	Epoxy Resin	0.02286	Silica Fused	60676-86-0	0.0206	48.38	90
				Epoxy Resin	Proprietary	0.0011	2.69	5
				Phenol Resin	Proprietary	0.0008	1.88	3.5
				Carbon Black	1333-86-4	0.0001	0.27	0.5
				Brominated Epoxy Resin	40039-93-8	0.0001	0.27	0.5
				Antimony trioxide	1309-64-4	0.0001	0.27	0.5
Total Package weight			0.04252					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%